All measurement taken with 360mA load, 12V input and 20MHz BWL unless noted.

**Efficiency**

The efficiency is shown below:

![Efficiency Graph](image)

**Ripple and Noise**

Output Ripple, 20mV/div
Measured 53.3mV peak to peak:
Input Ripple, 20mV/div
Measured 42.0mV peak to peak:

Dynamic Loading

0A to 360mA load step; 36mA/usec, 500mV/div, 1msec/div
Measured 1.27V peak to peak:

180mA to 360mA load step; 36mA/usec, 100mV/div, 1msec/div
Measured 384mV peak to peak:
**Turn On Response**

360mA load, 2msec/div:

![Graph 1](image1)

0A load, 2msec/div:

![Graph 2](image2)

**Loop Stability**

\[ BW = 5.6\text{KHz} \quad PM = 69\text{ Degrees} \quad GM = 13\text{dB} \]
Thermal Plot

Top Side:

Bottom Side:
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